AURIX™ TC3x Variants - China edition

About this document

Scope and purpose

This document is an addendum to the TC3x Product Data Sheet and User's Manual, listing all planned product variants, key parameters such as memory size and optional features.

The User's Manual lists functions implemented on the Silicon, but this document counts functions that are pinning dependent; that is functions are counted that are connected to at least one package pin. As pins are overlaid with several functions the pinning needs to be checked (see Product Data Sheet) to determine the number of usable functions in an application.

Naming conventions

Prefix:

- SAK: $T_{ambient}$ Temperature Range from -40°C up to +125°C

Feature Package:

- P: Standard feature
- E: Emulation device with all features of the emulated standard type, additionally full MCDS, overlay functionality for calibration, AGBT as trace interface for development (depending on the package)
- V,Z,M: Customer Specific
- A: ADAS ext. Memory
- T: ADAS + emulation
- X: Extended Feature device. These products contain the extended memory (EMEM) of the ADAS subsystem. The ADAS peripherals SPU and RIF are not available
- F: Extended Flash
- G: Additional Connectivity
- H: ADAS Standard feature
- N: Standard feature with AMU

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1 TC3x variants - China edition

The following table lists the TC3x variants - China edition

1.1 TC39x BD step

A table listing the TC39x BD step variants.

Table 1 TC39x_BD step

SAK-TC397XX-256F300C	SAK-TC397XP-256F300C	SAK-TC399XP-256F300C
Step		
BD	BD	BD
Production Status		
Standard	Standard	Standard
Package Type		
PG-LFBGA-292	PG-LFBGA-292	PG-LFBGA-516
Pinout		
LFBGA 0.8 mm	LFBGA 0.8 mm	LFBGA 0.8 mm
Reference Silicon		
TC39x	TC39x	TC39x
Temperature Range (Ambient)		
SAK	SAK	SAK
Chip ID ***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***		
0xAF019793	0x8F019793	0x8F019993
Cores / Checker Cores		
6/4	6/4	6/4
Max. Freq. (MHz)		
300	300	300
Program Flash (MB)		
16	16	16
Data Flash0 (single-ended) (KB)		
1024	1024	1024
Total SRAM (without EMEM and Cache) (KB)		
2528	2528	2528
EMEM Size (KB)		
4096	0	0
DSPR (KB)		

(table continues...)

1 TC3x variants - China edition

Table 1 (continued) TC39x_BD step

SAK-TC397XX-256F300C	SAK-TC397XP-256F300C	SAK-TC399XP-256F300C
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other	240 in CPU0&1; 96 other
DLMU (KB)		
64 per CPU	64 per CPU	64 per CPU
PSPR (KB)		
64 per CPU	64 per CPU	64 per CPU
LMU (KB)		
768	768	768
DAM (KB)		
128	128	128
AMU[1)]		
No	No	No
ADC (Primary Groups/Channels)		
5/40	5/40	8/64
ADC (Secondary Groups/Channels)		
4/60	4/60	4/60
ADC (Fast Compare Channels)		
8	8	8
ADC (EDSADC Channels)		
6	6	14
CAN (Modules/Nodes)		
3/3x4	3/3x4	3/3x4
FlexRay (Modules/Channels)		
2/2x2	2/2x2	2/2x2
HSSL Modules		
2	2	2
ASCLIN Modules / with ASC & LIN / with 3-wire SPI		
12/12/11	12/12/11	12/12/12
QSPI Modules / with LVDS		
6/2	6/2	6/2
SENT Channels		
20	20	25
MSC Modules		

(table continues...)

1 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

1 TC3x variants - China edition

Table 1 (continued) TC39x_BD step

SAK-TC397XX-256F300C	SAK-TC397XP-256F300C	SAK-TC399XP-256F300C
2	2	4
PSI5 Channels		
4	4	4
PSI5-S Module		
Yes	Yes	Yes
SDMMC Module		
Yes	Yes	Yes
Max. Ethernet Availability: 1GBit/100Mbit/No		
1Gbit/s	1Gbit/s	1Gbit/s
MCDS Availability[2)]		
MCDS	MCDS	MCDS
ADAS Cluster Available		
No	No	No
CIF		
No	No	No
HSM Available		
Yes	Yes	Yes

2 MCDS is not intended for use in productive devices. It may not be tested and is not covered by the safety case. For this functionality, please refer to the AURIX 2G Emulation device Data Sheet.

1.2 TC38x AE step

A table listing the TC38x AE step variants.

Table 2 TC38x_AE step

SAK-TC387QP-160F300C	SAK-TC389QP-160F300C
Step	
AE	AE
Production Status	
Standard	Standard
Package Type	
PG-LFBGA-292	PG-FBGA-516
Pinout	
LFBGA 0.8 mm	LFBGA 0.8 mm
Reference Silicon	
TC38x	TC38x
Temperature Range (Ambient)	
SAK	SAK
Chip ID ***Attention:*** ***The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***	
0x8C008784	0x8C008984
Cores / Checker Cores	
4/2	4/2
Max. Freq. (MHz)	
300	300
Program Flash (MB)	
10	10
Data Flash0 (single-ended) (KB)	
512	512
Total SRAM (without EMEM and Cache) (KB)	
1376	1376
EMEM Size (KB)	
0	0
DSPR (KB)	
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other
DLMU (KB)	
64 per CPU	64 per CPU

(table continues...)

1 TC3x variants - China edition

Table 2 (continued) TC38x_AE step

SAK-TC387QP-160F300C	SAK-TC389QP-160F300C
PSPR (KB)	
64 per CPU	64 per CPU
LMU (KB)	
128	128
DAM (KB)	
64	64
AMU[3)]	
No	No
ADC (Primary Groups/Channels)	
5/40	8/64
ADC (Secondary Groups/Channels)	
4/60	4/60
ADC (Fast Compare Channels)	
4	4
ADC (EDSADC Channels)	
6	10
CAN (Modules/Nodes)	
3/3x4	3/3x4
FlexRay (Modules/Channels)	
2/2x2	2/2x2
HSSL Modules	
1	1
ASCLIN Modules / with ASC & LIN / with 3-wire SPI	
24/24/11	24/24/12
QSPI Modules / with LVDS	
5/2	5/2
SENT Channels	
20	25
MSC Modules	
2	3
PSI5 Channels	
4	4

(table continues...)

3 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

1 TC3x variants - China edition

Table 2 (continued) TC38x_AE step

SAK-TC387QP-160F300C	SAK-TC389QP-160F300C
PSI5-S Module	
Yes	Yes
SDMMC Module	
No	No
Max. Ethernet Availability: 1GBit/100Mbit/No	
1Gbit/s	1Gbit/s
MCDS Availability	
miniMCDS	miniMCDS
ADAS Cluster Available	
No	No
CIF	
No	No
HSM Available	
Yes	Yes

1.3 TC37x AA step

A table listing the TC37x AA step variants.

Table 3 TC37x_AA step

SAK-TC377TP-96F300C	SAK-TC375TP-96F300C
Step	
AA	AA
Production Status	
Standard	Standard
Package Type	
PG-LFBGA-292	PG-QFP-176
Pinout	
LFBGA 0.8 mm	LQFP 0.5 mm
Reference Silicon	
TC37x	TC37x
Temperature Range (Ambient)	
SAK	SAK
Chip ID ***Attention:*** ***The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***	
0x89007780	0x89007580
Cores / Checker Cores	
3/2	3/2
Max. Freq. (MHz)	
300	300
Program Flash (MB)	
6	6
Data Flash0 (single-ended) (KB)	
256	256
Total SRAM (without EMEM and Cache) (KB)	
992	992
EMEM Size (KB)	
0	0
DSPR (KB)	
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other
DLMU (KB)	
64 per CPU	64 per CPU

(table continues...)

1 TC3x variants - China edition

Table 3 (continued) TC37x_AA step

SAK-TC377TP-96F300C	SAK-TC375TP-96F300C
PSPR (KB)	
64 per CPU	64 per CPU
LMU (KB)	
0	0
DAM (KB)	
32	32
AMU[4]	
No	No
ADC (Primary Groups/Channels)	
4/32	4/25
ADC (Secondary Groups/Channels)	
4/60	4/45
ADC (Fast Compare Channels)	
4	4
ADC (EDSADC Channels)	
6	6
CAN (Modules/Nodes)	
2/2x4	2/2x4
FlexRay (Modules/Channels)	
1/1x2	1/1x2
HSSL Modules	
1	1
ASCLIN Modules / with ASC & LIN / with 3-wire SPI	
12/12/11	12/12/10
QSPI Modules / with LVDS	
5/2	5/2
SENT Channels	
15	15
MSC Modules	
2	2
PSI5 Channels	
2	2

(table continues...)

[4] AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

1 TC3x variants - China edition

Table 3 (continued) TC37x_AA step

SAK-TC377TP-96F300C	SAK-TC375TP-96F300C
PSI5-S Module	
Yes	Yes
SDMMC Module	
No	No
Max. Ethernet Availability: 1GBit/100Mbit/No	
1Gbit/s	100Mbit/s (RMII)
MCDS Availability	
miniMCDS	miniMCDS
ADAS Cluster Available	
No	No
CIF	
No	No
HSM Available	
Yes	Yes

1.4 TC36x AA step

A table listing the TC36x AA step variants.

Table 4 TC36x AA step

SAK-TC367DP-64F300C	SAK-TC364DP-64F300C	SAK-TC366DP-64F300C
Step		
AA	AA	AA
Production Status		
Standard	Standard	Standard
Package Type		
PG-LFBGA-292	PG-QFP-144	PG-LFBGA-180
Pinout		
LFBGA 0.8 mm	TQFP 0.4 mm	LFBGA 0.8 mm
Reference Silicon		
TC36x	TC36x	TC36x
Temperature Range (Ambient)		
SAK	SAK	SAK
Chip ID ***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***		
0x87006780	0x87006480	0x87006680
Cores / Checker Cores		
2/2	2/2	2/2
Max. Freq. (MHz)		
300	300	300
Program Flash (MB)		
4	4	4
Data Flash0 (single-ended) (KB)		
128	128	128
Total SRAM (without EMEM and Cache) (KB)		
576	576	576
EMEM Size (KB)		
0	0	0
DSPR (KB)		
192 per CPU	192 per CPU	192 per CPU
DLMU (KB)		
64 per CPU	64 per CPU	64 per CPU

(table continues...)

Table 4 (continued) TC36x AA step

SAK-TC367DP-64F300C	SAK-TC364DP-64F300C	SAK-TC366DP-64F300C
PSPR (KB)		
32 per CPU	32 per CPU	32 per CPU
LMU (KB)		
0	0	0
DAM (KB)		
0	0	0
AMU[5)]		
No	No	No
ADC (Primary Groups/Channels)		
4/32	4/16	4/19
ADC (Secondary Groups/Channels)		
2/28	2/21	2/18
ADC (Fast Compare Channels)		
2	2	2
ADC (EDSADC Channels)		
4	4	4
CAN (Modules/Nodes)		
2/2x4	2/2x4	2/2x4
FlexRay (Modules/Channels)		
1/1x2	1/1x2	1/1x2
HSSL Modules		
1	1	1
ASCLIN Modules / with ASC & LIN / with 3-wire SPI		
12/12/10	12/12/8	12/12/9
QSPI Modules / with LVDS		
4/1	4/1	4/1
SENT Channels		
10	10	10
MSC Modules		
1	1	1
PSI5 Channels		
2	2	2

(table continues...)

5 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

Table 4 (continued) TC36x AA step

SAK-TC367DP-64F300C	SAK-TC364DP-64F300C	SAK-TC366DP-64F300C
PSI5-S Module		
Yes	Yes	Yes
SDMMC Module		
No	No	No
Max. Ethernet Availability: 1GBit/100Mbit/No		
1Gbit/s	100Mbit/s (RMII)	100Mbit/s (RMII)
MCDS Availability		
No	No	No
ADAS Cluster Available		
No	No	No
CIF		
No	No	No
HSM Available		
Yes	Yes	Yes

1.5 TC35x AB step

A table listing the TC35x AB step variants.

Table 5 TC35x AB step

SAK-TC357TA-64F300C	SAK-TC357TH-64F300C
Step	
AB	AB
Production Status	
Standard	Standard
Package Type	
PG-LFBGA-292	PG-LFBGA-292
Pinout	
ADAS	ADAS
Reference Silicon	
TC35x	TC35x
Temperature Range (Ambient)	
SAK	SAK
Chip ID ***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***	
0xB7015781	0xF7015781
Cores / Checker Cores	
3/2	3/2
Max. Freq. (MHz)	
300	300
Program Flash (MB)	
4	4
Data Flash0 (single-ended) (KB)	
128	128
Total SRAM (without EMEM and Cache) (KB)	
1472	960
EMEM Size (KB)	
2048	2048
DSPR (KB)	
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other
DLMU (KB)	
64 per CPU	64 per CPU

(table continues...)

1 TC3x variants - China edition

Table 5 (continued) TC35x AB step

SAK-TC357TA-64F300C	SAK-TC357TH-64F300C
PSPR (KB)	
64 per CPU	64 per CPU
LMU (KB)	
512	0
DAM (KB)	
0	0
AMU[6)]	
No	No
ADC (Primary Groups/Channels)	
2/16	2/16
ADC (Secondary Groups/Channels)	
0	0
ADC (Fast Compare Channels)	
0	0
ADC (EDSADC Channels)	
0	0
CAN (Modules/Nodes)	
2/2x4	2/2x4
FlexRay (Modules/Channels)	
1/1x2	1/1x2
HSSL Modules	
0	0
ASCLIN Modules / with ASC & LIN / with 3-wire SPI	
4/4/4	4/4/4
QSPI Modules / with LVDS	
4/0	4/0
SENT Channels	
0	0
MSC Modules	
0	0
PSI5 Channels	
0	0

(table continues...)

6 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

Table 5 (continued) TC35x AB step

SAK-TC357TA-64F300C	SAK-TC357TH-64F300C
PSI5-S Module	
No	No
SDMMC Module	
No	No
Max. Ethernet Availability: 1GBit/100Mbit/No	
1Gbit/s	1Gbit/s
MCDS Availability	
MCDSlight	MCDSlight
ADAS Cluster Available	
Yes	Yes
CIF	
No	No
HSM Available	
Yes	Yes

1.6 TC33xEXT AA step

A table listing the TC33xEXT AA step variants.

Table 6 TC33xEXT_AA step

	SAK-TC337DA-32F200C
Step	
	AA
Production Status	
	Standard
Package Type	
	PG-LFBGA-292
Pinout	
	ADAS
Reference Silicon	
	TC33xEXT
Temperature Range (Ambient)	
	SAK
Chip ID ***Attention**: The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.*	
	0xB4013780
Cores / Checker Cores	
	2/1
Max. Freq. (MHz)	
	200
Program Flash (MB)	
	2
Data Flash0 (single-ended) (KB)	
	128
Total SRAM (without EMEM and Cache) (KB)	
	456
EMEM Size (KB)	
	1024
DSPR (KB)	
	192 in CPU0; 96 in CPU1
DLMU (KB)	
	8 in CPU0; 64 in CPU1

(table continues...)

1 TC3x variants - China edition

Table 6 (continued) TC33xEXT_AA step

	SAK-TC337DA-32F200C
PSPR (KB)	
	32 in CPU0; 64 in CPU1
LMU (KB)	
	0
DAM (KB)	
	0
AMU	
	No
ADC (Primary Groups/Channels)	
	6/40
ADC (Secondary Groups/Channels)	
	0
ADC (Fast Compare Channels)	
	0
ADC (EDSADC Channels)	
	0
CAN (Modules/Nodes)	
	1/1x4
FlexRay (Modules/Channels)	
	0
HSSL Modules	
	0
ASCLIN Modules / with ASC & LIN / with 3-wire SPI	
	6/6/6
QSPI Modules / with LVDS	
	4/0
SENT Channels	
	6
MSC Modules	
	0
PSI5 Channels	
	0
PSI5-S Module	

(table continues...)

1 TC3x variants - China edition

Table 6 (continued) TC33xEXT_AA step

	SAK-TC337DA-32F200C
	No
SDMMC Module	
	Yes
Max. Ethernet Availability: 1GBit/100Mbit/No	
	1Gbit/s
MCDS Availability	
	MCDSlight
ADAS Cluster Available	
	Yes
CIF	
	No
HSM Available	
	Yes

1.7 TC33x AA step

A table listing the TC33x AA step variants.

Table 7 TC33x AA step

SAK-TC334LP-32F200C	SAK-TC336LP-32F200C	SAK-TC334LP-32F300C	SAK-TC333LP-32F300C
Step			
AA	AA	AA	AA
Production Status			
Standard	Standard	Standard	Standard
Package Type			
PG-QFP-144	PG-LFBGA-180	PG-QFP-144	PG-QFP-100
Pinout			
TQFP 0.4 mm	LFBGA 0.8 mm	TQFP 0.4 mm	TQFP 0.4 mm
Reference Silicon			
TC33x	TC33x	TC33x	TC33x
Temperature Range (Ambient)			
SAK	SAK	SAK	SAK
Chip ID ***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.***			
0x84003480	0x84003680	0x84003480	0x84003380
Cores / Checker Cores			
1/1	1/1	1/1	1/1
Max. Freq. (MHz)			
200	200	300	300
Program Flash (MB)			
2	2	2	2
Data Flash0 (single-ended) (KB)			
128	128	128	128
Total SRAM (without EMEM and Cache) (KB)			
208	208	208	208
EMEM Size (KB)			
0	0	0	0
DSPR (KB)			
192	192	192	192
DLMU (KB)			
8 in CPU0	8 in CPU0	8 in CPU0	8 in CPU0

(table continues...)

1 TC3x variants - China edition

Table 7 (continued) TC33x AA step

SAK-TC334LP-32F200C	SAK-TC336LP-32F200C	SAK-TC334LP-32F300C	SAK-TC333LP-32F300C
PSPR (KB)			
8 in CPU0	8 in CPU0	8 in CPU0	8 in CPU0
LMU (KB)			
0	0	0	0
DAM (KB)			
0	0	0	0
AMU[7)]			
No	No	No	No
ADC (Primary Groups/Channels)			
2/16	2/16	2/16	2/15
ADC (Secondary Groups/Channels)			
2/26	2/26	2/26	1/15
ADC (Fast Compare Channels)			
0	0	0	0
ADC (EDSADC Channels)			
0	0	0	0
CAN (Modules/Nodes)			
2/8	2/8	2/8	2/6
FlexRay (Modules/Channels)			
1/2	1/2	1/2	1/2
HSSL Modules			
0	0	0	0
ASCLIN Modules / with ASC & LIN / with 3-wire SPI			
12/12/10	12/12/10	12/12/10	5/5/5
QSPI Modules / with LVDS			
4/0	4/0	4/0	4/0
SENT Channels			
6	6	6	6
MSC Modules			
0	0	0	0
PSI5 Channels			
0	0	0	0

(table continues...)

7 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

1 TC3x variants - China edition

Table 7 (continued) TC33x AA step

SAK-TC334LP-32F200C	SAK-TC336LP-32F200C	SAK-TC334LP-32F300C	SAK-TC333LP-32F300C
PSI5-S Module			
No	No	No	No
SDMMC Module			
No	No	No	No
Max. Ethernet Availability: 1GBit/100Mbit/No			
No	No	No	No
MCDS Availability			
No	No	No	No
ADAS Cluster Available			
No	No	No	No
CIF			
No	No	No	No
HSM Available			
Yes	Yes	Yes	Yes

Revision history

Document version	Date of release	Description of changes
V1.0	2025-12-12	• First release
V1.1	2026-06-26	• Chapter 1 is updated with the new variants namely SAK-TC399XP-256F300C SAK-TC389QP-160F300C SAK-TC375TP-96F300C SAK-TC366DP-64F300C SAK-TC357TH-64F300C SAK-TC336LP-32F200C SAK-TC334LP-32F300C SAK-TC333LP-32F300C

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Edition 2026-06

Published by

Infineon Technologies AG

81726 Munich, Germany

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Document reference
IFX-pyn1754056806360

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